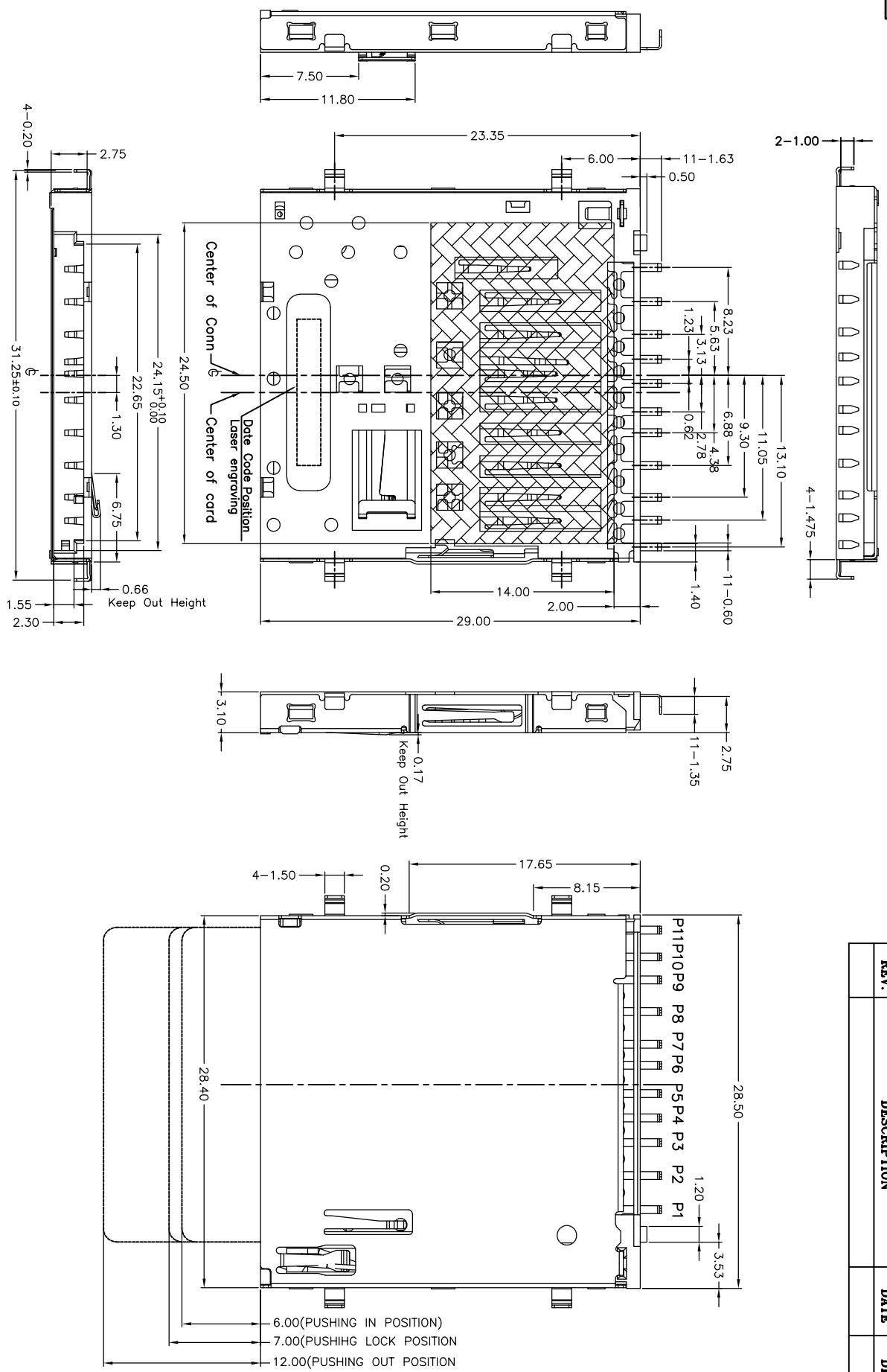


RoHS Compliant

1 2 3 4 5 6 7 8

REVISIONS			
REV.	DESCRIPTION	DATE	DESIGN



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TOLERANCES UNLESS OTHERWISE SPECIFIED:

X	± 0.35	X'	±	S'
.XX	± 0.25	.X'	±	Z'
.XXX	± 0.15	.XX'	±	1'

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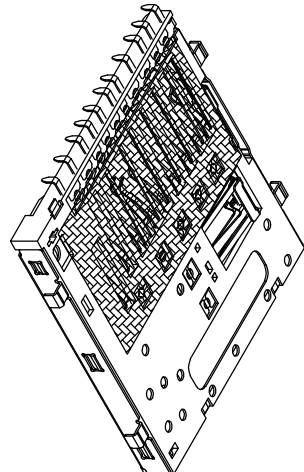
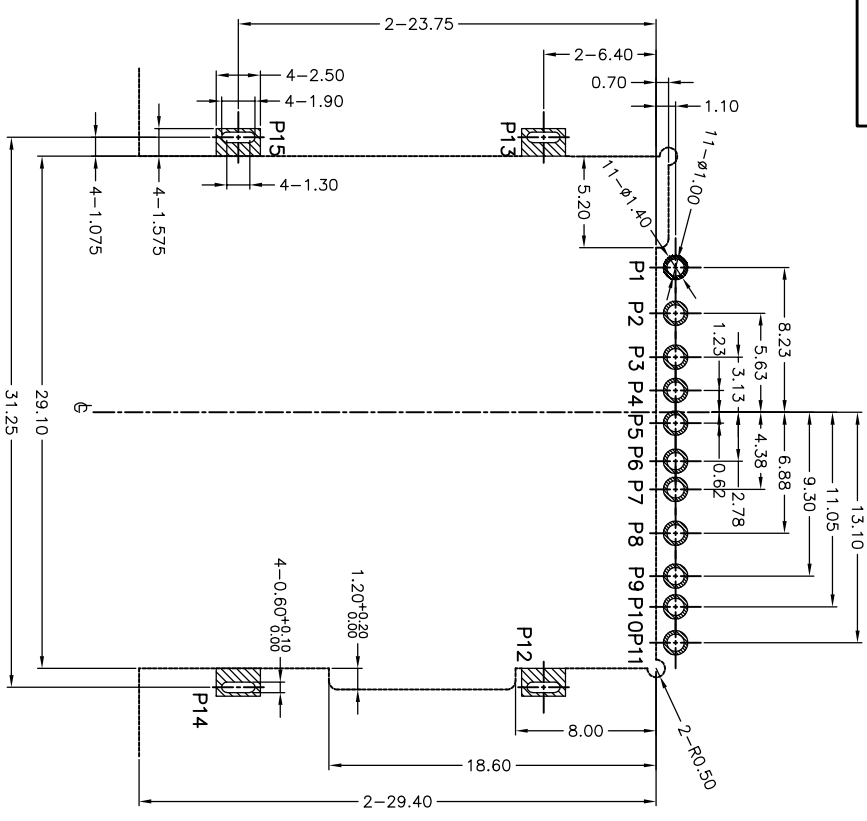
DESIGN: I.L DATE: 2017.3.1
CHECKED: C.W DATE: 2017.3.1
APPROVED: C.W DATE: 2017.3.1

TITLE: SD P/P 板下沉板 2.75 mm DIP
(防 MMC)

MATERIAL:	PART NO:	SIZE:
C.W	SD-11XXSR-003	A4
FINSH:	DWG NO:	SHEET:
C.W	SD-11XXSR-003	1 OF 3

REV: A UNIT mm SCALE 1=1 QUALITY SYMBOLS 1 2 3 4 5 6 7 8

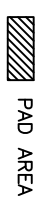
RoHS Compliant



Pin Define

Connector Pin No.	SD Card Pin No.	Pin Define
P1	P9	DATA2
P2	P1	DATA3
P3	P2	DATA1
P4	P3	CD
P5	P4	VSS1
P6	P5	VDD
P7	P6	CLK
P8	P7	VSS2
P9	P8	DATO
P10	P9	DATI
P11	P10	W/P
P12	P11	GND
P13	P12	GND
P14	P13	GND
P15	P14	GND

RECOMMENDED PCB Layout
(TOLERANCE:±0.05)



WITHOUT CARD	CARD INSERTED:LOCK	CARD INSERTED:UNLOCK
W/P #11 GND #12	W/P #11 GND #12	W/P #11 GND #12
C/D #04 GND #12	C/D #04 GND #12	C/D #04 GND #12

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REV: A	UNIT mm	SCALE 1=1	QUALITY SYMBOLS
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TOLERANCES UNLESS OTHERWISE SPECIFIED:

X	± 0.35	X'	± 0.25
XX	± 0.25	X''	± 0.15
XXX	± 0.15	XXX'	± 0.10

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REVISIONS		
REV.	DESCRIPTION	DATE

Specification

Can accord with management standards for environment-related substances to be controlled

***Electrical Characteristics:**
Contact Current Rating:0.5 Amperes.
Dielectric Withstanding Voltage:AC500V r.m.s.
Insulation Resistance:1000 MΩ Minimum.
Contact Resistance:100 mΩ Maximum.

***Environmental:**
Operating Temperature:-20°C~+85°C.
Mating Cycles:10,000 Insertions.

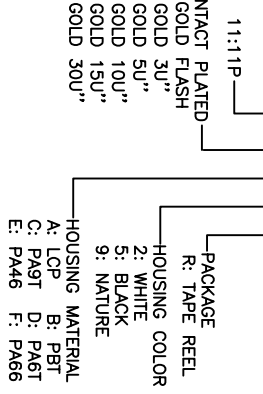
***Mechanical Characteristics:**
Card Push Insertion/Out Force:1.00kgf Maximum
Contact Separation Force:0.20kgf Minimum.

***Material:**
Insulator:LCP UL 94V-0 Rated.
Contact:Copper Alloy,T=0.15
Shell:Stainless Steel,T=0.20

***PLATING:**
contact area: Au plating over Ni(Ni 30 u")
solder tail area: matte tin plating over Ni(Ni 50 u")
shell: solderable Ni plating over all
solder tail area: matte tin plating over Ni(Ni 50 u")

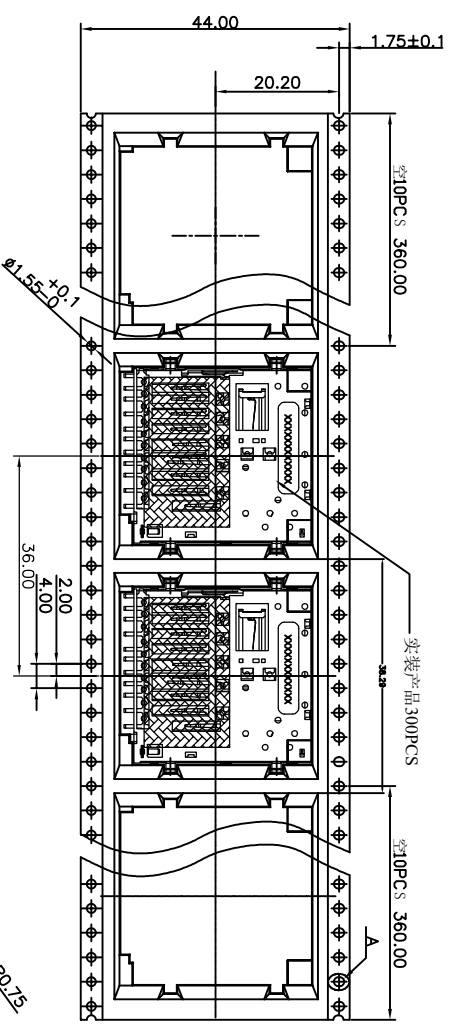
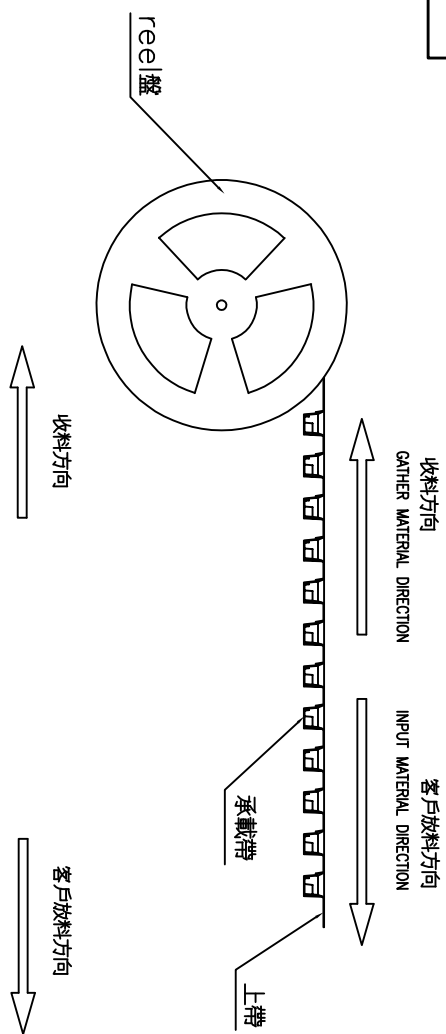
PART NO. INFORMATION

SD -11 X X 5 R - 003

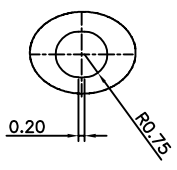


DESIGN: I.L	DATE: 2017.3.1	TITLE: SD P/P 板下沉板 2.75 mm DIP
CHECKED: C.W	DATE: 2017.3.1	MATERIAL: (防 MMC)
APPROVED: C.W	DATE: 2017.3.1	PART NO: SD-11XX5R-003
FINSH: C.W	DATE: 2017.3.1	DWG NO: SD-11XX5R-003
		SIZE: A4
		SHEET: 2 OF 3

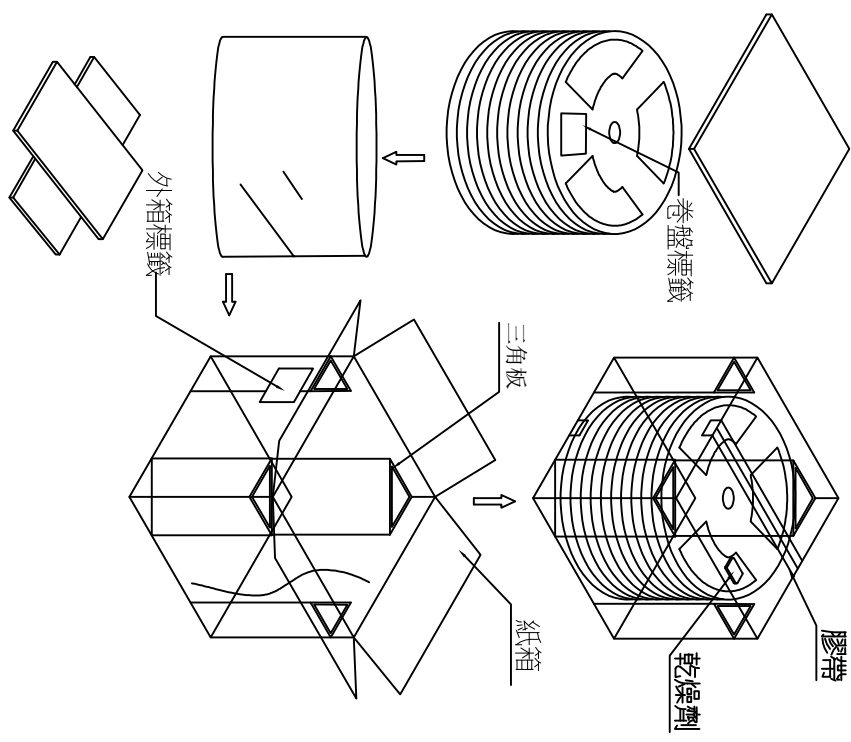
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PART NAME	C-D11127517-8
QUANTITY OF PER REEL	300PCS/REEL
QUANTITY OF PER CARTON	6*300=1800PCS/CARTON



DETAIL: A
SCALE:5:1



REVISIONS		
REV.	DESCRIPTION	DATE

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TOLERANCES UNLESS OTHERWISE SPECIFIED:

± 0.35	± 0.25	± 0.15
± 0.25	± 0.15	± 0.10
± 0.15	± 0.10	± 0.05

REV: A	UNIT mm	SCALE 1=1	QUALITY SYMBOLS
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DESIGN: I.L	DATE: 2017.3.1
CHECKED: C.W	DATE: 2017.3.1
APPROVED: C.W	DATE: 2017.3.1

TITLE: SD P/P 板下沉板 2.75mm DIP (防 MMC) 包装规范	PART NO: SD-11XXSR-003	SIZE: A4
FINSH: SD-11XXSR-003	DWG NO: SD-11XXSR-003	SHEET: 3 OF 3